

In the Specification

Paragraph 0023 on page 6 has been amended as follows:

Galvanoplastic processes are generally known, for which reason they are not discussed in any more detail here. In principle, this takes place by the mirror elements 9 being brought into their position on the basic body 8 and the entire unit then being cathodically connected in an electrolytic bath and the desired material, for example Cu or Ni, being used as the anode, so that the parts can grow together to form one unit. In this way, for example, the growing on of an intermediate layer 10, such as a copper layer of any desired thickness can be achieved. ~~Additionally, as is known for galvanoplastic processing, figure~~ Figure 2b illustrates mirror elements 9 ~~may be partially covered by a protection layer 30 (indicated by dashed lines) before the galvanoplastic processing to~~ prevent with the intermediate layer 10 being formed over selected portions of the mirror elements 9 during the galvanoplastic process.